

18<sup>th</sup> IEEE Electrical Design of Advanced Packaging and Systems Symposium

EDAPS 2025

December 15<sup>th</sup> to 17<sup>th</sup>, 2025, Hokkaido University, Sapporo, Japan

The IEEE Electrical Design of Advanced Packaging and Systems (EDAPS) Symposium is the premier international conference in the Asia-Pacific region to share the latest advances in design, modeling, simulation, and measurement related to electrical issues at the chip, packaging, and system levels. EDAPS 2025 will be held in Sapporo, Japan from 15 to 17 December 2025 and will include paper presentations, industry exhibitions, workshops and tutorials. The technical program of the symposium will not only focus on the current electrical design issues but also brings out the topics on IC design, SiP/SoP packaging, EMC/EMI and most importantly the challenging design issues in advanced 3D-IC, chiplets, heterogeneous integration, and the application of machine learning in EDA. For more information, please visit <http://edaps.org>.

Call for Papers: Topics	
<div>✓ Advanced Packages: 2D, 2.xD, 3D, 3.5D</div> <div>✓ Interposers: Silicon, RDL, Bridge, Glass</div> <div>✓ Interconnects: Hybrid Bonding, uBump, TSV, Carbon Nanotube, Graphene</div> <div>✓ High-Speed Interfaces: UCle, SerDes, HBM, LPDDR, GDDR, DDR</div> <div>✓ PDN: Backside PDN, Deep Trench Capacitor, IVR</div> <div>✓ EDA: AI-Based Tools, Multi-Physics, ADK</div>	<div>✓ Machine Learning, Deep learning, LLM</div> <div>✓ Modeling: Model Order Reduction, Macro-modeling</div> <div>✓ RF/mmWave/Terahertz Antenna and Packages</div> <div>✓ Co-Package Optics (CPO)</div> <div>✓ Power Devices &amp; Modules: GaN/SiC/Diamond</div> <div>✓ EMC/EMI/EMS: ex. Automotive Applications</div>

Important Dates

Paper Submission  
July 18<sup>th</sup>, 2025

Acceptance Notification  
September 1<sup>th</sup>, 2025

Final Paper Submission  
October 10<sup>th</sup>, 2025

Awards & Grants
<div><div>• Best conference paper award</div><div>• Best poster award</div><div>• Best student paper award</div><div>• Student travel grants</div></div>

Paper Submission
<div><div>• <b>Double-column and three-page</b> PDF file format</div><div>• Hardcopy submission will NOT be accepted</div></div>

**General Chair:**  
Hideki Sasaki, Rapidus Corporation

**Technical Program Co-Chairs:**  
Yutaka Uematsu, Hitachi Ltd  
Kazuyuki Nakagawa, Renesas Electronics

**Local Arrangement Chair:**  
Seiya Kasai, Hokkaido University

**Secretary:**  
Daisuke Ohshima, Chitose Institute of Science and Technology

**Publication Co-Chairs:**  
Minoru Watanabe, Okayama University  
Soshi Shimomura, Hitachi Ltd.

**Financial Chair:**  
Kiyoshi Hasegawa, Rapidus Corporation



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